

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

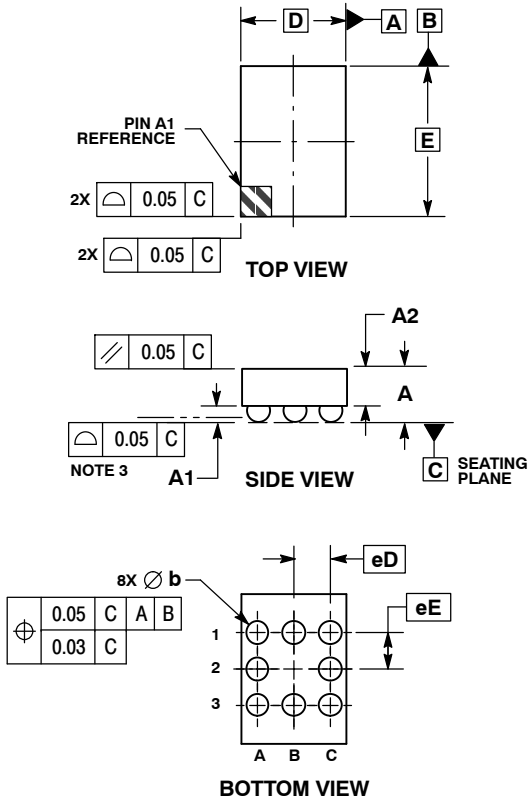
ON Semiconductor®



SCALE 4:1

WLCSP8, 1.155x1.655
CASE 567DH
ISSUE O

DATE 12 JAN 2012

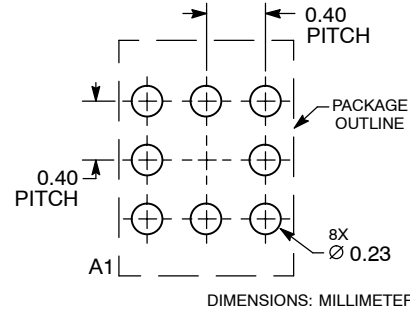


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.50	0.60
A1	0.17	0.24
A2	0.36 REF	
b	0.24	0.29
D	1.155 BSC	
E	1.655 BSC	
eD	0.40 BSC	
eE	0.40 BSC	

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	WLCSP8, 1.155X1.655	PAGE 1 OF 2

